

## **APPARATUS AND METHODS FOR TOOL MARK FREE STITCH BONDING**

### **ABSTRACT**

Apparatus and method for tool mark free stitch bonding. In some embodiments, a method for wire bonding can include feeding a wire through a capillary tip and attaching a first end of the wire to a first location, thereby forming a ball bond. The method can further include moving the capillary tip towards a second location while the wire feeds out of the capillary tip. The method can further include attaching a second end of the wire to the second location while preventing contact between the capillary tip and the second location, thereby forming a stitch bond without a tool mark at the second location.

Fig. 11